



IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (Currently Amended): A printed circuit board comprising:

a core substrate comprising a first resin substrate, a second resin substrate having an opening and a third resin substrate in a multilayer manner while interposing bonding plates, the first resin substrate including a first surface and a second surface opposite to the first surface;

insulating layers and conductive circuit layers alternately laminated on the first surface of the first resin substrate ~~core substrate~~;

a capacitor formed in the opening of the second resin substrate;

a first conductive pad formed on the second surface of the first resin substrate and connected to an electrode of the capacitor;

a second conductive pad formed on the second surface of the first resin substrate and connected to the other electrode of the capacitor;

a first via hole formed in the first resin substrate, the first via hole directly connected to the first conductive pad and a conductive circuit on the core substrate; and

a second via hole formed in the first resin substrate, the second via hole directly connected to the second conductive pad and a conductive circuit on the core substrate.

Claim 2 (Currently Amended): [[A]] The printed circuit board according to claim 1, wherein each of said bonding plates has a core impregnated with a thermosetting resin.

Claim 3 (Currently Amended): [[A]] The printed circuit board according to claim 1, wherein each of said first, second and third resin substrates having a core made of glass cloth and impregnated with a resin.

Claim 4 (Currently Amended): ~~[[A]]~~ The printed circuit board according to claim 1, wherein the second resin substrate has a plurality of openings and a plurality of capacitors are formed in the openings.

Claim 5 (Currently Amended): ~~[[A]]~~ The printed circuit board according to claim 1, wherein the conductor circuits are formed on said second resin substrate.

Claims 6-8 (Canceled).

Claim 9 (Currently Amended): ~~[[A]]~~ The printed circuit board according to claim 1, further comprising:

a metal film formed on the electrode of said capacitor.

Claim 10 (Currently Amended): ~~[[A]]~~ The printed circuit board according to claim 9, wherein the metal film formed on the electrode of said capacitor is a plated film ~~mainly consisting of~~ comprising copper.

Claims 11-14 (Canceled).

Claim 15 (Currently Amended): A printed circuit board constituted by alternately laminating insulating layers and conductive circuits on a core substrate containing a ceramic capacitor, wherein

the core substrate containing said capacitor comprises a first resin substrate, a second resin substrate having an opening for containing the ceramic capacitor and a third resin substrate in a multilayer manner while interposing bonding plates,

said first resin substrate and said ceramic capacitor are coupled to each other by an insulating bonding agent and a coefficient of thermal expansion of the insulating bonding agent is lower than ~~that~~ a coefficient of thermal expansion of said first resin substrate,

a conductive pad is formed on the first resin substrate and connected to an electrode of the capacitor, and

a via hole, through which the conductive pad is connected to the conductive circuit on the core substrate, is formed in the first resin substrate.

Claims 16-78 (Canceled).

Claim 79 (Currently Amended): ~~[[A]]~~ The printed circuit board according to claim ~~[[75]]~~ 15, further comprising:

a metal film formed on the electrode of the capacitor.

Claim 80 (Currently Amended): ~~[[A]]~~ The printed circuit board according to claim 79, wherein the metal film formed on the electrode of the capacitor is a plated film ~~mainly consisting of~~ comprising copper.

Claim 81 (Currently Amended): ~~[[A]]~~ The printed circuit board according to claim ~~[[75]]~~ 15, wherein ~~the capacitor is a ceramic capacitor and~~ each of said bonding plates has a core impregnated with a thermosetting resin.

Claim 82 (Currently Amended): ~~[[A]] The printed circuit board according to claim~~  
~~[[75]] 15, wherein the capacitor is a ceramic capacitor and each of said first, second and third~~  
resin substrates having a core made of glass cloth and impregnated with a resin.

Claim 83 (Currently Amended): ~~[[A]] The printed circuit board according to claim 75,~~  
15, further comprising a plurality of bumps formed on an outer layer of the insulating layers  
and constituting a bump area,

wherein an IC chip is to be mounted on the bump area.

Claim 84 (Currently Amended): ~~[[A]] The printed circuit board according to claim 1,~~  
further comprising a plurality of bumps formed on an outer layer of the insulating layers and  
constituting a bump area, wherein at least one of the bumps is electrically connected to the  
electrode of the capacitor through a via hole formed immediately below the bump area.

Claim 85 (Currently Amended): ~~[[A]] The printed circuit board according to claim~~  
84, wherein an IC chip is to be mounted on the bump area.

Claim 86 (Previously Presented): A printed circuit board comprising:  
a core substrate comprising a first resin substrate, a second resin substrate having an  
opening and a third resin substrate in a multilayer manner while interposing bonding plates;  
insulating layers and conductive circuit layers alternately laminated on the core  
substrate; and  
a ceramic capacitor formed in the opening of the second resin substrate,  
wherein each of said first, second and third resin substrates has a core made of glass  
cloth and impregnated with a resin.

Claim 87 (Currently Amended): ~~[[A]]~~ The printed circuit board according to claim 86, further comprising:

a conductive pad formed on the first resin substrate and connected to an electrode of the capacitor; and

a via hole formed in the first resin substrate, the via hole directly connected to the conductive pad and the conductive circuit on the core substrate.

Claim 88 (Currently Amended): ~~[[A]]~~ The printed circuit board according to claim 86, wherein ~~the capacitor is a ceramic capacitor and~~ each of said bonding plates has a core impregnated with a thermosetting resin.

Claim 89 (Currently Amended): ~~[[A]]~~ The printed circuit board according to claim 86, further comprising a plurality of bumps formed on an outer layer of the insulating layers and constituting a bump area, wherein at least one of the bumps is electrically connected to the electrode of the capacitor through a via hole formed immediately below the bump area.

Claim 90 (Currently Amended): ~~[[A]]~~ The printed circuit board according to claim 89, wherein an IC chip is to be mounted on the bump area.